

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT5771707

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
MENG-LIANG LIN	10/04/2019
PO-HAO TSAI	10/04/2019
PO-YAO CHUANG	10/04/2019
YI-WEN WU	10/04/2019
TECHI WONG	10/04/2019
SHIN-PUU JENG	10/04/2019
RECEIVING PARTY DATA	
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City:	HSINCHU
State/Country:	TAIWAN
Postal Code:	300-78
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16654187
CORRESPONDENCE DATA	
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NAME OF SUBMITTER:	DANIEL R. MCCLURE
SIGNATURE:	/Daniel R. McClure/
DATE SIGNED:	10/16/2019

Total Attachments: 2

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PATENT

REEL: 050731 FRAME: 0567

ASSIGNMENT

WHEREAS, Meng-Liang LIN, Po-Hao TSAI, Po-Yao CHUANG, Yi-Wen WU, Tech WONG and Shin-Puu JENG

hereafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **STRUCTURE AND FORMATION METHOD OF CHIP PACKAGE WITH FAN-OUT FEATURE**

Filed: _____ Serial No. _____
Executed on: _____

WHEREAS, Taiwan Semiconductor Manufacturing Co., Ltd., of No. 8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu 300-78, Taiwan R.O.C., hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

ASSIGNMENT

2019/10/4
Date
Meng-Liang Lin
Name: Meng-Liang LIN

2019/10/4
Date
Po-Hao Tsai
Name: Po-Hao TSAI

2019/10/4
Date
Po-Yao Chuang
Name: Po-Yao CHUANG

2019/10/4
Date
Yi-Wen Wu
Name: Yi-Wen WU

2019/10/4
Date
Teeho Wong
Name: Teehi WONG

2019/10/4
Date
Shin-Puu Jeng
Name: Shin-Puu JENG